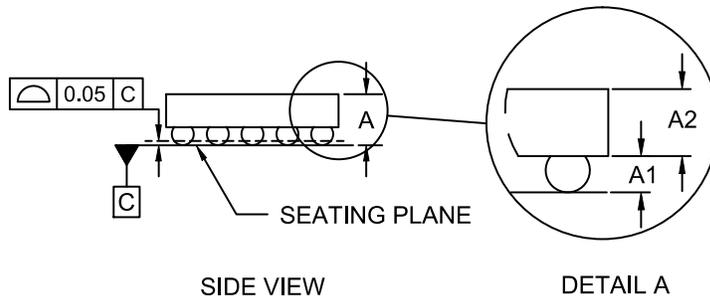
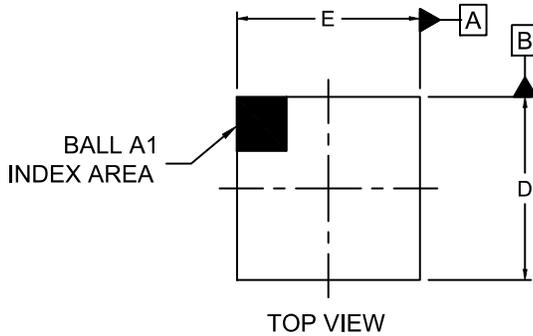


**WLCSP25 2.16x2.16x0.586**  
CASE 567QT  
ISSUE A

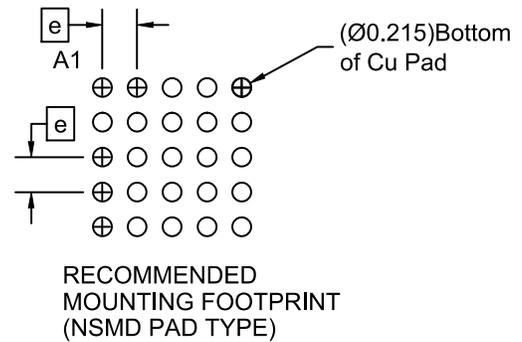
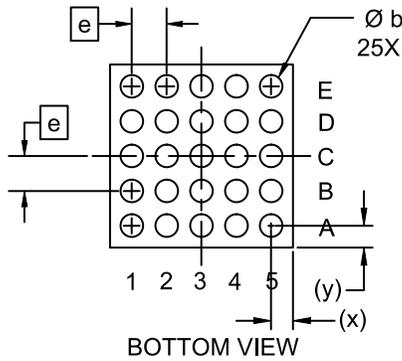
DATE 13 MAR 2018



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.547	0.586	0.625
A1	0.188	0.208	0.228
A2	0.360	0.378	0.396
b	0.24	0.26	0.28
D	2.13	2.16	2.19
E	2.13	2.16	2.19
e	0.40 BSC		
x	0.265	0.280	0.295
y	0.265	0.280	0.295



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